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TMS2019
 148th Annual Meeting & Exhibition

CALL FOR ABSTRACTS

March 10–14, 2019
 San Antonio, Texas, USA

SUBMIT AN ABSTRACT TO:

ELECTRONIC MATERIALS

Advanced Microelectronic Packaging, Emerging Interconnection Technology, and Pb-free Solder

Continuing advances in microelectronic, optoelectronic, and nanoelectronic devices require new materials and technologies to meet the increasing electrical, thermal, mechanical, reliability, performance, and environmental demands placed on interconnects and packaging at all levels. This symposium will address current researches in Packaging Materials and Process, including lead-free solder, alternative interconnects, conductive adhesive, epoxy, substrates, 3D packaging, wafer level packaging, quality, reliability, and failure analysis.

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Abstract Deadline is July 1, 2018.
 Submit online at www.programmaster.org/TMS2019

Questions?
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